**Plastic Packages for Integrated Circuits**

**Package Outline Drawing**

M10.118A (JEDEC MO-187-BA)
10 LEAD MINI SMALL OUTLINE PLASTIC PACKAGE (MSOP)
Rev 0, 9/09

Plastic or metal protrusions of 0.15 mm max per side are not included.
Dimensions “D” and “E1” are measured at Datum Plane “H”.
Plastic interlead protrusions of 0.25 mm max per side are not included.
Dimensioning and tolerancing conform to AMSE Y14.5m-1994.

**NOTES:**

1. Dimensions are in millimeters.
2. Dimensioning and tolerancing conform to AMSE Y14.5m-1994.
3. Plastic or metal protrusions of 0.15 mm max per side are not included.
4. Plastic interlead protrusions of 0.25 mm max per side are not included.
5. Dimensions “D” and “E1” are measured at Datum Plane “H”.
6. This replaces existing drawing # MDP0043 MSOP10L.